



Fast and easy solution to potting and encapsulating electronic components





#### The fast and easy solution for potting and encapsulating electronic components

Sealing components with potting and encapsulating compounds prevents corrosion and ensures long-term integrity of a device, but using traditional methods, such as epoxy resins or silicone can prove time consuming, costly and inefficient.

A new manufacturing process has been developed for a black polyamide potting compound that can be dispensed through conventional 12mm (½") hot melt glue guns. This process has been specifically designed for the electronic, automotive and aerospace industries.

#### Benefits

Tecbond adhesives have a number of advantages over traditional potting and encapsulating methods:

- Fast: the adhesive is quick to apply, and fast to set
- Easy to use: no mixing, no waste, and no consumable parts
- Clean: clean application, with no messy residue once the adhesive has cooled
- Cost effective: fast and accurate application with no cleaning or flushing required
- Efficient: no need for ovens to accelerate the curing process
- No shelf life: tecbond adhesives are clean to handle and can be stored for long periods without risk of expiry
- No chemicals or solvents: tecbond adhesive is completely environmentally friendly, non-toxic and contains no solvents

#### Potting & encapsulating adhesives

Tecbond hot melt adhesive provides instant, permanent bonding on a vast range of materials without the use of harmful solvents.

The tecbond 7718FR adhesive has a very low viscosity, so flows easily into the smallest cavities. Black in colour, it will prevent the encapsulated components being visible and, in turn, further protect your technology. The adhesive is fire retardant, has a very fast setting time, and is suitable for:

- Component stabilisation
- Attaching components to PC boards
- Fixing and securing
- Coil terminating battery packs
- Vibration protection
- Strain relief of cables
- Potting
- Wire staking

The glue is supplied in air-tight, resealable foil bags to stop exposure to moisture and keep the glue in optimum condition for use.

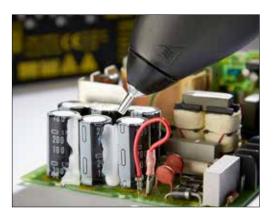
Tecbond 7718FR is supplied in 12mm ( $\frac{1}{2}$ ") x 250mm (10") glue sticks and packed in 10 stick resealable foil bags (10 x 10 stick bags per carton).



#### Disadvantages of other systems

Other system like epoxy resins or silicones can prove to be:

- Time consuming
- Costly
- Inefficient





Formulation	Description	Colour	Open time	Viscosity
7718FR	Black, low viscosity potting and encapsulation polyamide adhesive	Black	Short	Low

### Tec<sup>™</sup> glue guns

Tec glue guns are low-cost capital items, highly portable, and designed to be totally reliable in tough industrial environments. Just load the tool with glue and it will melt it on demand as the trigger is pulled.

#### tec 305-12

Light industrial 12mm ( $\frac{1}{2}$ ") glue gun, lightweight and easy to use, illuminated on/off switch, removable stand, adjustable full hand trigger and replaceable nozzle.

Melt rate
Glue size
Voltage
Wattage
Heater
Temp Control
Hotmelt gun °C (°F)
Lowmelt gun °C (°F)
Power cable
Weight
Packaging

900g (2lbs)/hr 12mm (½") glue stick 110-240V 20W (150W) PTC Self-regulating heater 195°C (380°F) 130°C (265°F) 2m (6½ ft) 250g (9oz) PET blister (10 per ctn)





tec 305 potting and encapsulating kit available



#### gas-tec 600

The gas-tec 600 is a totally portable, robust compact hot melt glue gun that runs on butane gas. It does not require mains electricity or batteries but operates on gas, which can be easily refuelled from cigarette lighter refill cans.

Melt rate
Glue size
Voltage
Wattage
Heater
Temp Control
Hotmelt gun °C (°F)
Lowmelt gun °C (°F)
Power cable
Weight
Packaging

1.7kg (3.7lbs)/hr 12mm (½") glue stick Gas powered 185W (equivalent) Catalytic Thermostatic gas valve 195°C (380°F) n/a Cordless 390g (14oz) PET blister (10 per ctn)





gastec 600 potting and encapsulating kit available



## tec 820-12

Adjustable temperature, heavy duty medium size 12mm (½") glue gun. Robust and easy to use, fast recovery, medium output, 2 minute warm up time & illuminated on/off switch.

Melt rate Glue size Voltage Wattage Heater Temp Control Hotmelt gun °C (°F) Lowmelt gun °C (°F) Power cable Weight Packaging



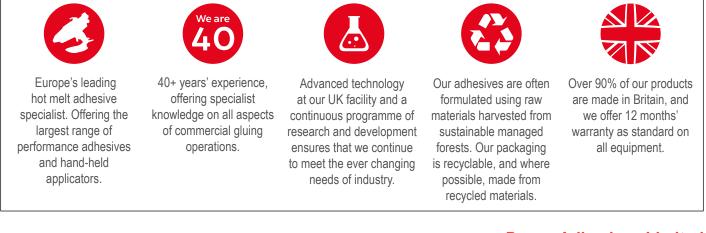




tec 820 potting and encapsulating kit available



	sories		Carry cas	е	
Tec mat	Jueguns			DDP003-SP/	
*# <u></u>	TEC MAT			rry-case, can be usec ec 800 series guns. C ccessories.	
Reference	Description	tec 305 gastec 600 tec 820	Reference	Description	tec 305 gastec 600 tec 820
TEC MAT	Silicone rubber drip mat protects work	surface.			
	Size 200mm x 200mm x 1.75mm		DDP003-SPARES	Carry case	
Gun star		MDC009	DDP003-SPARES	Carry case	SK-800-MAGSTAND
Gun star	nds		DDP003-SPARES	Carry case	Bastec color datatec color fec g302 fec g302
Ì	nds	MDC009	DDP003-SPARES	Carry case	0
Reference	nds	MDC009	DDP003-SPARES	Carry case	8



# power adhesives

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